APPLICATION OF SURROGATE MODELING IN VARIATION-AWARE MACROMODEL AND CIRCUIT DESIGN

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This paper presents surrogate modeling as a solution to variation-aware macromodeling, circuit design, and Abstract: device modeling. A scalable and high-fidelity IO buffer macromodel is created by integrating surrogate modeling with a physically-based model structure. Circuit performance surrogate models with design and variation parameters are efficient for design space exploration and performance yield analysis. Surrogate models of the main device characteristics are generated in order to assess the effects of variability in analog circuits. Surrogate-based optimization has great potential to speed up complex circuit design.

INTRODUCTION 1

The efforts to create high performance analog/mixsignal circuits are increasing as system complexities and uncontrollable variations. It is required to capture the effects of variations in circuit modeling and design analysis, in order to create a robustly behaving design. However, this is a nontrivial task. In this paper, we apply surrogate modeling to handle the high-dimensional parameters and complex responses in variation-aware circuit macromodel, design analysis, and device model. We demonstrate the benefits of using surrogate modeling in enhancing the accuracy, flexibility and efficiency in those applications.

2 SURROGATE-BASED MACROMODEL

Large system design and validation are becoming more and more complex, both in terms of CPU memory required and simulation time consumed. Using macromodels of the sub-circuits is a way to reduce the complexity. We demonstrate a new methodology of using surrogate modelling in developing high-fidelity and flexible macromodels. In the new method, an equivalent circuit structure is used to capture the static and dynamic circuit behaviors, while surrogate modeling is used to approximate each element over a range of Process-

Voltage-Temperature (PVT) parameters, so that the macromodel is able to dynamically adapt to the PVT variations in analysis.

2.1 **Proposed Macromodel Structure**

The new method is applied to develop surrogatebased Input/Output (IO) buffer macromodel(Zhu and Franzon, 2009). The most popular approach to IO modelling is to use the traditional table-based inputoutput buffer information specification (IBIS) (IO Buffer Information Specification, Online). IBIS models are simple, portable, IP-protected, and fast in simulation. However, they are unable to simulate continuous PVT variations and unsuitable for statistical analysis. We propose a new type of macromodel, called the surrogate IBIS model, to solve the problem. Figure 1 shows the proposed surrogate IBIS macromodel structure that is composed of physically-based equivalent model elements. I_{pu} and I_{pd} represent the nonlinear output current. Time-variant coefficients K_{pu} and K_{pd} determine the partial turn-on of the pull-up/down networks during switching transitions. C_{power} and C_{gnd} represent the nonlinear parasitic capacitance between the output and the supply rails. Global surrogate modeling techniques (Gorissen et al., 2009) are used to extract the accurate model elements with PVT effects. The goal of the global surrogate modeling is to create a model that approximates the behavior of the element on the entire domain. so that the surrogate model expressions can then be used as a full replacement for the original circuit elements.

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To achieve high-fidelity, data from t ransistor-level SPICE circuit simulations are used for fitting the models, and an accuracy target is defined for the modeling iterations. The surrogate buffer macromodels obtained are portable and they can be easily implemented in a variety of modeling languages, e.g. Verilog-A.



Figure 1: Structural IO buffer macromodel template with surrogate model elements.

2.2 Macromodel Extraction

The method is demonstrated on a single-ended output buffer circuit shown in Figure 2. The circuit is designed in 180 nm CMOS process with a 3.3 V normal supply voltage. The threshold voltage variations ΔV_{th} in the MOS transistors are considered as the main process variations and they are assumed vary by $\pm 20\%$. The supply voltage V_s is assumed to fluctuate within $\pm 30\%$ of the nominal supply (3.3 V) and temperature (*T*) is set in the range of 0 to 100 °C. The Circuit simulations were performed using HSPICE 2009.03 SP1, and modeling construction was performed in MATLAB 2009b using the SUMO Toolbox version 7.0. (Gorissen et al., 2010).



Figure 2: Simplified schematic of the driver circuit.

Figure 3 (a) shows the transistor-level circuit simulations for modelling pull-up output current



Figure 3: Test-benches for extracting model elements: (a) pull-up current I_{pu} (b) rising/falling transition waveforms for K_{pu} and K_{pd} (c) illustration of 2EQ/2UK algorithm (d) output capacitance C_{gnd} and C_{power} .

 $I_{pu}(V_{s}, V_{pu}, T, \Delta V_{th})$. The input signal turns on the pull-up network and turns off the pull-down network. Similarly, the pull-down current model I_{pd} (V_S , V_{pd} , T, $\Delta V_{\rm th}$) was extracted by turning on the pull-down network and turning off the pull-up network. The time-variant transition coefficients K_{pu} and K_{pd} were obtained according to 2EQ/2UK algorithm (Muranyi, Online). Figure 3 (b) shows the test to obtain the switching output voltage waveforms. Figure 3(c) shows a simplified circuit to illustrate the 2EQ/2UK algorithm. The switching output voltage waveforms wfm_1 and wfm_2 were obtained with different terminal voltage V_{term}, and the unknown coefficients K_{pu} and K_{pd} could be derived by the equations

$$K_{pu}(t)I_{pu}(V_{wfm_1}(t)) - K_{pd}(t)I_{pd}(V_{wfm_1}(t)) - I_{out} = 0$$

$$K_{pu}(t)I_{pu}(V_{wfm_2}(t)) - K_{pd}(t)I_{pd}(V_{wfm_2}(t)) - I_{out} = 0$$
(1)

where $I_{out} = (V_{out} - V_{term}) / R_{load}$. I_{pu} and I_{pd} are the output current models.

The test setup for extracting the output parasitic capacitance is shown in Figure 3(d). An AC signal is attached to the output ports and the imaginary currents in the power and the ground ports are measured. The capacitances C_{power} and C_{gnd} were derived using

$$C_{\text{power}} = \frac{\Im(I_{\text{VCC}})}{2\pi f V_{\text{AC}}} , \quad C_{\text{gnd}} = \frac{-\Im(I_{\text{gnd}})}{2\pi f V_{\text{AC}}}$$
(2)

where $\Im(I_{\text{VCC}})$ and $\Im(I_{\text{gnd}})$ are the imaginary parts of the measured currents, f is the frequency of the AC source, and V_{AC} is the AC voltage amplitude. SIMULTECH 2011 - 1st International Conference on Simulation and Modeling Methodologies, Technologies and Applications

2.3 Test Results

To implement the new model, we modified the Verilog-A behavioural version IBIS model (LaBonte and Muranyi, Online) and applied the surrogate model expressions for the model elements. The surrogate models are implemented in the form of analog functions.

The modified IBIS model and transistor level model were compared in simulation. The accuracy of the macromodel is quantified by computing the timing error and the maximum relative voltage error. The timing error is defined as the time difference between the reference and the macromodel voltage responses measured for crossing half of the output voltage swing. The maximum relative voltage error is defined as the maximum error between the reference and macromodel voltage responses divided by the voltage swing.

The test setup is shown in Figure 4 where the driver is connected to a 0.75-m long lossy transmission line (RLGC model) with a load resistor. The use of transmission line makes reflections a very strong concern. The characteristic impedance of the transmission line is equal to 50 Ω . The data pattern for this study is a 1024 bit long pseudorandom bit sequence (PRBS) with 2-ns bit time. The lossy transmission line and the loading resistor R_{load} are the same.

Figure 5 shows the responses at the far-end of the transmission line under the nominal PVT condition $(V_s = 3.3 \text{ V}, \text{ process parameter } \Delta V_{\text{th}} = 0, T = 27 \text{ °C})$. In this case, the maximum timing error is 70 ps (3.5% of the bit-time) and the maximum relative voltage error is 6.45%. We examine the eye diagram of the output in Figure 5. The eye-width (*W*) is measured when the eye-height (*H*) is equal to 1 V. The results under different PVT conditions show that the eye-width differences within 0.04 ns (2% of the bit-time).

The proposed macromodel achieves good accuracy in the analysis. The macromodels obtained show good accuracy in capturing the effects of reflections and variations, and their scalability makes flexible design analysis possible.



Figure 4: Test setup for model validation.



Figure 5: Output voltage at far end of transmission line when input 1024 bit-long PRBS (partial). Grey solid line: transistor, Black dashed line: macromodel.

2 CIRCUIT DESIGN SPACE EXLPORATION

Advances in integrated circuit (IC) technologies have enabled the single-chip integration of multiple analog and digital functions, resulting in complex mixed-signal Systems-on-a-Chip (SoCs). Circuit designers are confronted with large design spaces and many design variables whose relationships need to be analyzed. In this situation, tasks such as sensitivity analysis, design space exploration and visualization become difficult, even if a single simulation takes only short time. The analyses are getting impractical when some of the circuit simulations are computationally expensive and timeconsuming.

Global surrogate modeling (Gorissen et al., 2009) could be a valuable asset to assist the circuit design analysis at an early stage. The method is a datadriven approximation which is to capture the global behavior of the circuit by only considering the input and output behavior. In our experiments, the surrogate models for the circuit performance (e.g. Sparameter, gain, power consumption, noise figure, etc) are constructed with design variables (e.g. transistor size, bias voltage, current, etc.) as input parameters. Transistor-level circuit simulations and performance measurements were setup for obtaining the modeling data. Adaptive sampling strategies can be used to make the sampling process interactive and efficient. An automatic flow is developed for the performance surrogate modeling (Figure 6).

Once the global surrogate model is constructed, it will help to speed up the sensitivity analysis, to assist the visualization of the design space, and to gain insight into the circuit behaviors. The models are reusable so that the designers can vary the specifications and constraints, and quickly see the changes in the feasible design space.



Figure 6: Adaptive surrogate-modeling flow with SPICE circuit simulations.

3 YIELD-AWARE CIRCUIT DESIGN

As IC technologies scale down to 65 nm and beyond, it is more challenging to create reliable and robust designs in the presence of large process (P) and environmental variations (e.g. supply voltage (V), temperature(T)) (Semiconductor Industry Associate). Without considering PVT fluctuations, the optimal circuit design would possibly minimize the cost functions by pushing many performance constraints to their boundaries, and comes up a design that is very sensitive to the variations. Therefore, we need to not only search for the optimal case at the nominal conditions, but also carefully treat the circuit robustness in the presence of variations. However, the fulfillment of all these requirements introduces more complications in circuit designs.

Yield is defined as the number of dies per wafer that meet all predefined performance metrics. Monte Carlo analysis is an important technique used for yield estimation. However, this method requires a large number of sampling points to achieve sufficient accuracy and therefore it is very timeconsuming.

We use performance models with variation information for quick yield analysis.

$$P = S(D, V) \tag{3}$$

Where \overline{D} represents the design parameters, and \overline{V} represents the variation parameters.

The constructed performance models quantize the

dependence among the device-level variations, design parameters, and the circuit-level performance so that it can be applied to estimate the performance yield.

One application of the variation-aware performance model is to obtain the yield-aware Pareto fronts which is best trade-offs of the overall circuit performance and the yield. In addition to searching for the general Pareto-optimal designs, performance yield at those design points is evaluated by using the variation-aware performance model. As a result, the yield-aware Pareto fronts can be generated. An illustration is shown in Figure 7. P_1 and P_2 are the performance to trade-off, and the curves are the Pareto fronts with different yield levels. The yield-aware Pareto fronts of sub-blocks could be further used in the yield-aware system design



Figure 7: Illustration of Pareto fronts with different yield levels.

4 SURROGATE-BASED DEVICE MODELING

Scaling of device sizes induced high variability of transistor parameters. There are two major reasons Firstly, quantum mechanics-based for this. phenomena such as the drain induced barrier lowering (DIBL) or gate tunnelling which were negligible in long-channel devices become more significant. Additional physics-based effects increased the dependence of many circuit design quantities including the drain current, I_{ds} , and device transconductance, g_m , on the transistor process parameters such as the oxide thickness, t_{ox} . Furthermore, the tolerance of semiconductor manufacturing components did not scale down as the transistor sizes shrink (Orshansky et al., 2008). As a consequence, the amount of uncertainty in the design quantities remained constant while device sizes become smaller leading to higher percentages of variability with respect to the nominal values of

the transistor process parameters. The experimental data revealed that the traditional process corner analysis might not reflect the real distribution of the critical transistor parameters such as the threshold voltage $V_{\rm th}$ (Saha, 2010) while the Monte Carlo analysis become more computationally intensive with increasing number of variability factors.

The response surface of design quantities which become more complex with the presence of extreme process variations can be accurately captured by surrogate modelling. Surrogate modelling aims to express the output quantity in terms of a few input parameters by evaluating a limited number of samples. These samples are employed by the basis functions which establish the response surface of the desired output. Coefficients of the basis functions should be optimized to minimize the modelling error. This approach has been applied to the problem of I_{ds} modelling in order to assess the effects of variability in analogue circuit building blocks, in particular, the differential amplifiers (Yelten et al.,to be published). In this paper, the modelling of g_m of n-channel transistors will be discussed.

 g_m is an important quantity for analogue circuits, particularly in determining the AC performance of amplifiers, mixers and voltage controlled oscillators. The modelling here is based on 65 nm device technology (IBM 10SF design kit) and uses six process parameters (t_{ox} , intrinsic threshold voltage $V_{\text{th},0}$, intrinsic drain-source resistance $R_{ds,0}$, intrinsic mobility μ_0 , channel length variation ΔL_{eff} , and channel doping N_{ch}) as input to the model in addition to the terminal voltages of the transistor (gate-source voltage V_{gs} , drain-source voltage V_{ds} , and bulksource voltage V_{bs}) and the temperature T. The choice of these process parameters is based on their physical origin which ensures a weak correlation between each parameter. BSIM model I_{ds} equations are analytically differentiated to yield g_m such that:

$$g_m = \partial I_{ds} / \partial V_{gs} \,. \tag{4}$$

The g_m expression is validated by extensive SPICE circuit simulations over the process corners and at temperature extremes so that it can be used to evaluate the samples, each composed of the ten elements described above. Although an analytic equation for g_m is used in this work, the modelling methodology is general and can employ simulations or measurement results given that they have the same input and output parameters.

Kriging basis functions are used to construct the surrogate model with the necessary coefficients being optimized using the MATLAB toolbox Design and Analysis of Computer Experiments (DACE) (Lophaven et al., URL). The device width is assumed to be 10 μ m. The finalized model is tested for accuracy using the root relative square error (RRSE) metric where RRSE can be given as:

$$RRSE = \sqrt{\frac{\sum_{i=1}^{N_T} (y_{model}(i) - y_{true}(i))^2}{\sum_{i=1}^{N_T} (y_{true}(i) - \frac{1}{N_T} \sum_{i=1}^{N_T} y_{true}(i))^2}}.$$
 (5)

In (5), N_T is the number of test samples. The g_m model is constructed using a total number of 2560 input samples, and tested with N_T =6400 samples other than the input samples. The resulting model yields an RRSE of 3.96% indicating to a high level of accuracy.

The model can be used to observe the changes in g_m with respect to its input parameters. Examples of this are provided in Figure 8. The graphs provide critical insight to the designer about the fundamental relations and trade-offs between the chosen process parameters, terminal voltages and temperature.

5 SURROGATE-BASED CIRCUIT OPTIMIZATION

Simulation-based circuit optimization creates a good opportunity for surrogate modeling, as the process requires a great number of iterative evaluations of objective functions. In optimization process, surrogate models are used to guide the search instead of achieving the global accuracy.

In the surrogate-based optimization process, generally there are two types of simulation models, a low-fidelity and a high-fidelity model. In our circuit design problems, the transistor-level circuit simulation is used for high-fidelity model while the built surrogate model is used for low-fidelity model. The general surrogate-based optimization process is shown in Figure 9 (Queipo et al., 2005).

We are interested in exploring Gaussian process based model (e.g. Kriging model) as an approximation method since Kriging model is able to provide estimation of the uncertainty in the prediction. Adaptive sampling methods (e.g. expected improvement (Forrester et al.,2008)) can be used to balance between the exploration (improving the general accuracy of the surrogate model) and exploitation (improving the accuracy of the surrogate model in the local optimum area) during optimization. An alternative method, space mapping (Koziel et al., 2008), maps the input/output



Figure 8: 3D graphs showing the trade-offs between the different inputs on the modelled gm.

space of a low-fidelity model to the input/output space of the high-fidelity model. These methods would be able to significantly improve the optimization efficiency when physically computational cheap low-fidelity models are available.

6 SUMMARY

This work presents the applications of surrogate modelling in variation-aware circuit modeling and



Figure 9: General surrogate-based optimization flow.

design analysis. Surrogate modeling enhances the accuracy and flexibility of IO macromodel, assets the design exploration and optimization with, and generates device model with critical variability parameters. The surrogate-based method demonstrates great benefits of reducing the complex and cost in variation-aware modeling and circuit design.

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